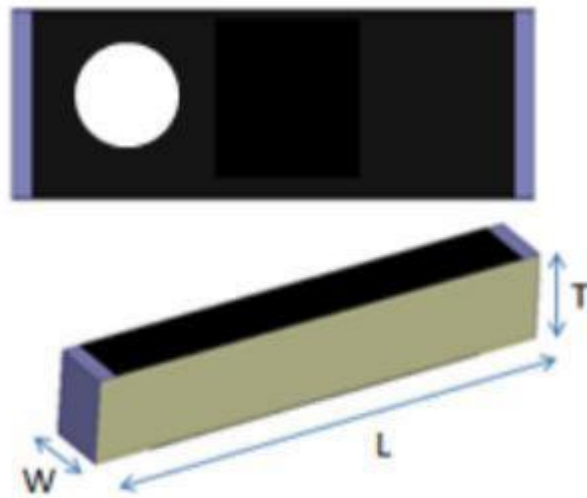


P/N:HLX321605A6

For Bluetooth / WLAN Applications



P/N:HLX321605A6

	Dimension (mm)
L	3.2 ± 0.20
W	1.6 ± 0.20
T	0.5 ± 0.10

P/N:HLX321605A6

Part Number Information

HLX **3** **21** **6** **05** **A6**
A **B** **C** **D** **E** **F**

A	Product Series	Antenna
B	Type	PIFA
C	Dimension L x W	3.2×1.6 mm (±0.2mm)
D	Material	Low Loss & High K material
E	Dimension T	0.5 ±0.10 mm
F	Product Name	A6

1. Electrical Specification

Specification		
Part Number	HLX321605A6	
Central Frequency	2450	MHz
Bandwidth	90 (Min.)	MHz
Return Loss	-9.6 (Max)	dB
Peak Gain	4.23	dBi
Impedance	50	Ohm
Operating Temperature	-40 ~ +85	°C
Maximum Power	1	W
Resistance to Soldering Heats	10 (@ 260°C)	sec.
Polarization	Linear	
Azimuth Beamwidth	Omni-directional	
Termination	Cu / Sn (Leadless)	

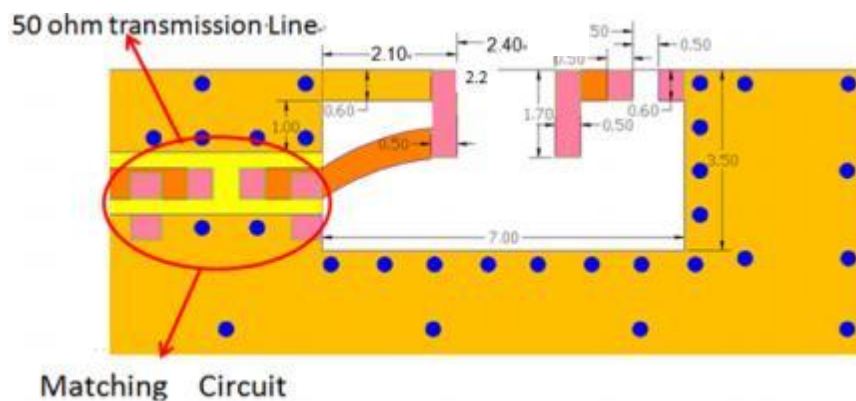
P/N:HLX321605A6

2. Recommended PCB Pattern (Unit : mm)

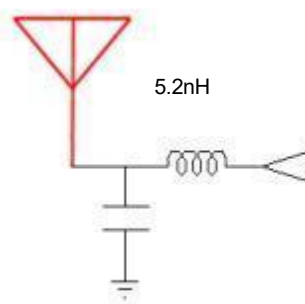
a.Evaluation Board Dimension



a-1.Layout Dimensions in Clearance area(Size=7.0*3.5mm)

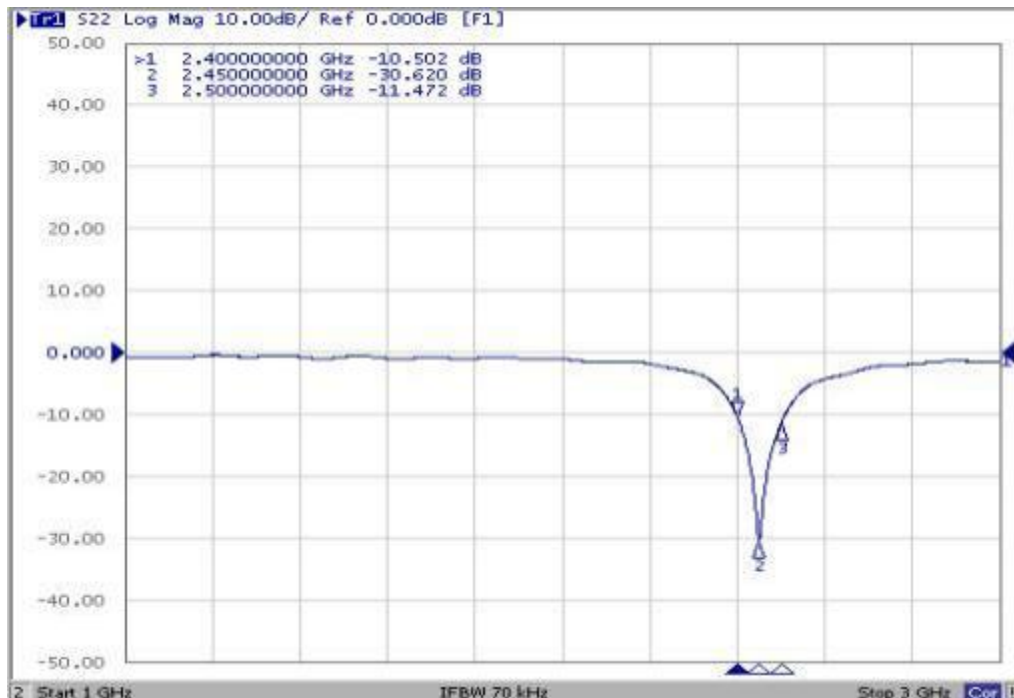


3. Suggested Matching Circuit

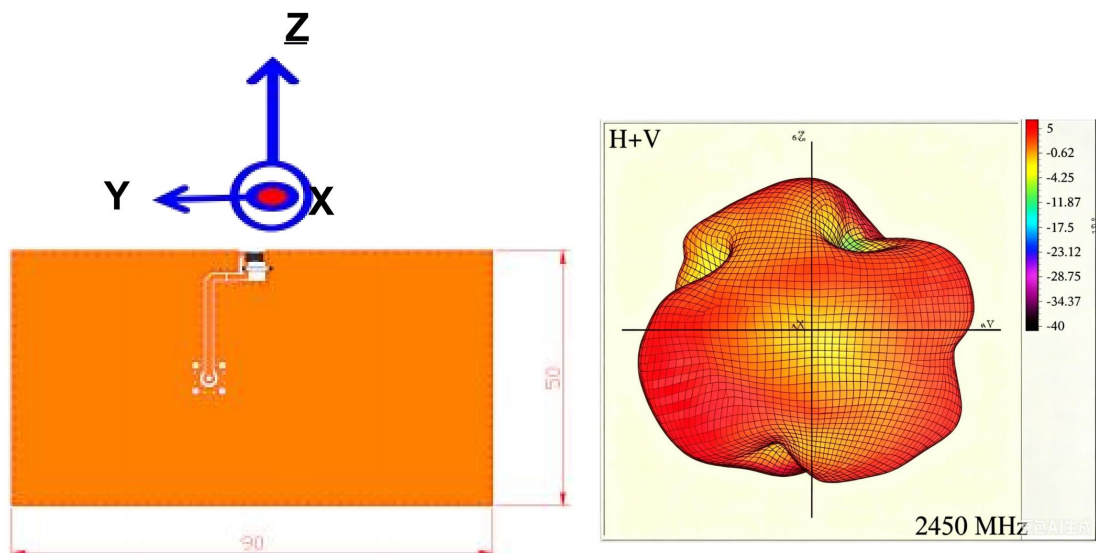


4. Measurement Results

a. Return Loss

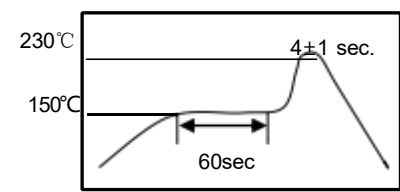
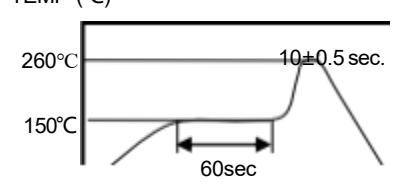


b. Radiation Pattern



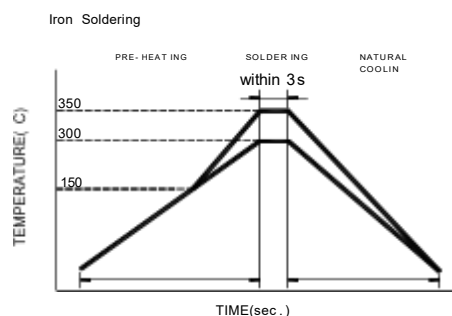
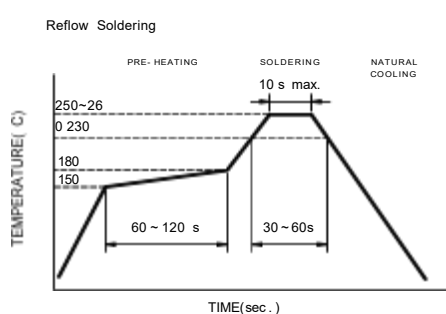
Frequency (MHz)	2400	2450	2500
Avg. Gain (dBi)	-1.37	-1.19	-1.49
Peck Gain (dBi)	1.81	4.23	2.75
Efficiency (%)	73	76	71

5. Reliability and Test Conditions

ITEM	REQUIREMENTS			TEST CONDITION	
Solderability	1. Wetting shall exceed 90% coverage 2. No visible mechanical damage TEMP (°C) 			Pre-heating temperature:150°C/60sec. Solder temperature:230±5°C Duration:4±1sec. Solder:Sn-Ag3.0-Cu0.5 Flux for lead free: rosin	
Solder heat Resistance	1. No visible mechanical damage 2. Central Freq. change :within ±6% TEMP (°C) 			Pre-heating temperature:150°C/60sec. Solder temperature:260±5°C Duration:10±0.5sec. Solder:Sn-Ag3.0-Cu 0.5 Flux for lead free: rosin	
Component Adhesion (Push test)	1. No visible mechanical damage			The device should be reflow soldered(230±5°C for 10sec.) to a tinned copper substrate A dynameter force gauge should be applied the side of the component. The device must with-ST-F 0.5 Kg without failure of the termination attached to component.	
Component Adhesion (Pull test)	1. No visible mechanical damage			Insert 10cm wire into the remaining open eye bend ,the ends of even wire lengths upward and wind together. Terminal shall not be remarkably damaged.	
Thermal shock	1. No visible mechanical damage 2. Central Freq. change :within ±6%			+85°C=>30±3min -40°C=>30±3min Test cycle:10 cycles The chip shall be stabilized at normal condition for 2~3 hours before measuring.	
	Phase	Temperature(°C)			Time(min)
	1	+85±5°C			30±3
	2	Room Temperature			Within 3sec
	3	-40±2°C			30±3
	4	Room Temperature			Within 3sec
Resistance to High Temperature	1. No visible mechanical damage 2. Central Freq. change :within ±6% 3. No disconnection or short circuit.			Temperature: 85±5°C Duration: 1000±12hrs The chip shall be stabilized at normal condition for 2~3 hours before measuring.	
Resistance to Low Temperature	1. No visible mechanical damage 2. Central Freq. change :within ±6% 3. No disconnection or short circuit.			Temperature:-40±5°C Duration: 1000±12hrs The chip shall be stabilized at normal condition for 2~3 hours before measuring.	
Humidity	1. No visible mechanical damage 2. Central Freq. change :within ±6% 3. No disconnection or short circuit.			Temperature: 40±2°C Humidity: 90% to 95% RH Duration: 1000±12hrs The chip shall be stabilized at normal condition for 2~3 hours before measuring.	

6.Soldering and Mounting

Mildly activated rosin fluxes are preferred. The minimum amount of solder can lead to damage from the stresses caused by the difference in coefficients of expansion between solder, chip and substrate. The terminations are suitable for all wave and re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.



Recommended temperature profiles for re-flow soldering in Figure 1.

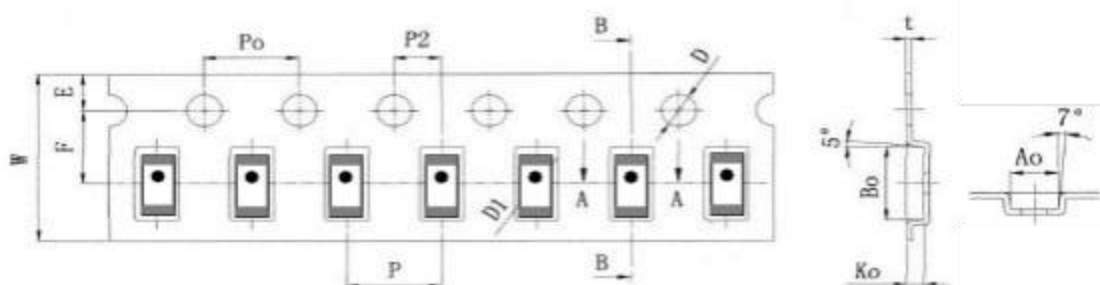
Products attachment with a soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended.

- .Preheat circuit and products to 150°C
- .Never contact the ceramic with the iron tip
- .Use a 20 watt soldering iron with tip diameter of 1.0mm
- .280°C tip temperature (max)
- .1.0mm tip diameter (max)
- .Limit soldering time to 3 sec.

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7.Packaging Information

◆ Tape Specification:

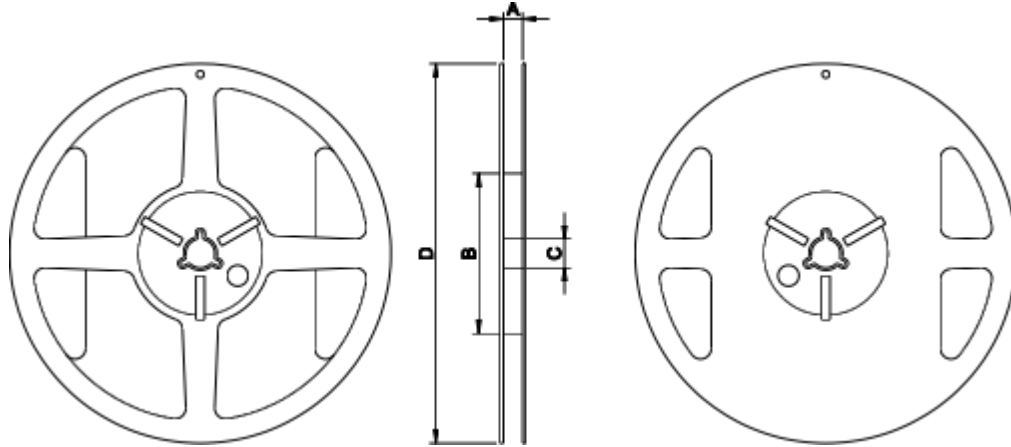


外觀	規格	公差
W	8.00	±0.10
P	4.00	±0.10
E	1.75	±0.10
F	3.50	±0.05
P2	2.00	±0.05
D	1.50	+0.10 -0.00
D1	1.00	±0.10
P0	4.00	±0.10
10P0	40.00	±0.20

外觀	規格	公差
Ao	1.85	±0.10
Bo	3.50	±0.10
Ko	0.73	±0.10
t	0.23	±0.05

P/N:HLX321605A6

◆ Reel Specification: (7", $\Phi 180$ mm)



7" x 8 mm

Tape Width(mm)	A(mm)	B(mm)	C(mm)	D(mm)	Chip/Reel(pcs)
8	9.0 $\pm$ 0.5	60 $\pm$ 2	13.5 $\pm$ 0.5	178 $\pm$ 2	6000

8.Storage and Transportation Information

Storage Conditions

To maintain the solderability of terminal electrodes:

1. Temperature and humidity conditions: -10~ 40℃ and 30~70% RH.
2. Recommended products should be used within 6 months from the time of delivery.
3. The packaging material should be kept where no chlorine or sulfur exists in the air.

Transportation Conditions

1. Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
2. The use of tweezers or vacuum pick up is strongly recommended for individual components.
3. Bulk handling should ensure that abrasion and mechanical shock are minimized.